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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/777,026	02/11/2004	Mark N. Kawaguchi	8033/ETCH	2197
55649 7590 10/12/2007 MOSER IP LAW GROUP / APPLIED MATERIALS, INC.		EXAMINER		
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2ND FLOOR SHREWSBUR	Y, NJ 07702		ART UNIT	PAPER NUMBER
•			1792	
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			NOTIFICATION DATE	DELIVERY MODE
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Please find below and/or attached an Office communication concerning this application or proceeding.

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		Application No.	Applicant(s)		
		10/777,026	KAWAGUCHI ET AL.		
	Office Action Summary	Examiner	Art Unit		
		Binh X. Tran	1765		
Period fo	The MAILING DATE of this communication app or Reply	ears on the cover sheet with the c	orrespondence address		
A SH WHIC - Exte after - If NC - Failu Any	ORTENED STATUTORY PERIOD FOR REPLY CHEVER IS LONGER, FROM THE MAILING DANSIONS of time may be available under the provisions of 37 CFR 1.13 SIX (6) MONTHS from the mailing date of this communication. Operiod for reply is specified above, the maximum statutory period we re to reply within the set or extended period for reply will, by statute, reply received by the Office later than three months after the mailing ed patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be tim vill apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	N. hely filed the mailing date of this communication. D (35 U.S.C. § 133).		
Status		•			
1)🛛	Responsive to communication(s) filed on 27 Se	eptember 2007.			
	This action is FINAL . 2b) This action is non-final.				
3)□	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is				
	closed in accordance with the practice under E	x parte Quayle, 1935 C.D. 11, 45	i3 O.G. 213.		
Dispositi	ion of Claims				
5) <u></u> . 6)⊠	Claim(s) <u>1-9,11-23,25-31 and 35-42</u> is/are penda) Of the above claim(s) is/are withdraw Claim(s) is/are allowed. Claim(s) <u>1-8,11,12,17-19,21-23,25-30 and 35-4</u> Claim(s) <u>9,13-16, 20, 31</u> is/are objected to. Claim(s) are subject to restriction and/or	vn from consideration. 12 is/are rejected.			
Applicati	on Papers				
9) 10)	The specification is objected to by the Examiner The drawing(s) filed on is/are: a) acce Applicant may not request that any objection to the of Replacement drawing sheet(s) including the correction The oath or declaration is objected to by the Examiner	epted or b) objected to by the Edrawing(s) be held in abeyance. See on is required if the drawing(s) is obj	e 37 CFR 1.85(a). ected to. See 37 CFR 1.121(d).		
Priority ι	ınder 35 U.S.C. § 119				
12) a)	Acknowledgment is made of a claim for foreign All b) Some * c) None of: 1. Certified copies of the priority documents 2. Certified copies of the priority documents 3. Copies of the certified copies of the priorical application from the International Bureausee the attached detailed Office action for a list of	s have been received. s have been received in Application ity documents have been receive (PCT Rule 17.2(a)).	on No ed in this National Stage		
	e of References Cited (PTO-892)	4) Interview Summary			
3) 🔲 Inforr	e of Draftsperson's Patent Drawing Review (PTO-948) nation Disclosure Statement(s) (PTO/SB/08) r No(s)/Mail Date	Paper No(s)/Mail Da 5) Notice of Informal Pa 6) Other:			

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DETAILED ACTION

Response to Arguments

1. Applicant's arguments, see pages 9-10, filed 9-27-2007, with respect to the rejection(s) of claim(s) 1-2, 4-8, 17-19, 21-22, 26-30 under 35 USC 103 as being unpatentable over Liu in view of Byun have been fully considered and are persuasive. Therefore, the previous final rejection (mailed on 07-27-2007) has been withdrawn. However, upon further consideration, a new ground(s) of final rejection is made as discussed below.

Claim Rejections - 35 USC § 103

- 2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 3. This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).

4. Claims 1-2, 4-8, 17-19, 21-22, 26-30, 38, 42 are rejected under 35 U.S.C. 103(a) as being unpatentable over Liu et al. (US 6,774,045 B1) in view of Narwankar et al. (US 6,204,203).

Respect to claims 1-2, 21-22 Liu discloses a method for removing halogencontaining residue from a substrate, (abstract), the method comprising the steps of:
 providing a substrate having a polysilicon layer on the substrate;
 etching the polysilicon layer and forming a halogen-containing residues,
comprising at least chlorine or bromine on the substrate, (Table 1-6, col. 2-6);

heating the etched substrate to the temperature at a temperature of 20-300 °C (col. 10 line5-18, 33-44, read on applicant's range of "at least 50 °C" and/or "50 °C to about 450 °C" for claims 2 and 22);

exposing the heated substrate to a plasma that removes the halogen-containing residues (col. 10 lines 10, 35, Fig 2, Fig 3, Table 5-6).

Liu fails to disclose heating the etch substrate in a non-plasma mixture comprising oxygen and nitrogen. However, Liu clearly teaches to heat the substrate. Narwankar teaches to heat the substrate at a temperature 400-650 °C in a non-plasma (i.e. using rapid thermal process) gas mixture comprising oxygen and nitrogen under rapid thermal annealing order to remove carbon from the surface (col. 7-8). It would have been obvious to one having ordinary skill in the art, at the time of invention, to modify Liu in view of Narwankar by heating using non-plasma mixture comprising oxygen and nitrogen because it will remove carbon from the surface (col. 7 lines 53-62).

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Respect to claims 4 and 26, Liu discloses the halogen-containing residue comprises bromine (col. 2 lines 1-10, Table 6). Respect to claim 5, and 27, Liu disclose the plasma comprises oxygen-containing gas (Table 5-6). Respect to claims 6 and 28, Liu disclose the oxygen-containing gas comprises oxygen, H₂O and an addictive gas comprise nitrogen (Table 5-6). Respect to claims 7 and 29, Liu discloses the halogen-containing residue comprises chlorine (Fig 4, Table 5-6). Respect to claims 8 and 30, Liu discloses the plasma comprises hydrogen-containing gas (i.e. H₂O, See Table 5-6). Respect to claims 17-18, Liu disclose the plasma comprises oxygen-containing gas at a pressure of 2 torr, at a duration about 30 seconds (Table 5, col. 5 lines 23-30). Respect to claims 19, Liu discloses maintaining the hydrogen-containing gas (H₂O)_s at a pressure of 2 torr (Table 5). Respect to claims 38 and 42, Narwankar disclose the substrate is heated at a pressure of 100 Torr (col. 7 lines 34-35).

5. Claims 3, 11-12, 23, 35-37, 39-41 rejected under 35 U.S.C. 103(a) as being unpatentable over Liu and Narwankar and as applied to claims 1-2, 4-8, 17-19, 21-22, 26-30, 38, 42 above, and further in view of Chen et al. (US 5,545,289).

Claims 3 and 23 differ from Liu and Narwankar by further discloses forming the plasma by energizing a gas mixture in a remote plasma reactor. However, Liu clearly teaches to form a plasma by energizing a gas mixture using microwave source. Chen teaches to form a plasma by energizing a gas mixture in a remote plasma reactor using a microwave source (Fig 2). It would have been obvious to one having ordinary skill in the art, at the time of invention, to modify Liu and Narwankar in view of Chen by using a remote plasma reactor because equivalent and substitution of one for the other would

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produce an expected result. Further, remote plasma reactor is well known in semiconductor art.

Claim 11 differs from Liu by the further specifying the exposing step comprises maintaining the temperature of the substrate at about 250 °C. However, Liu clearly teaches the temperature is a result effective variable varying from 20-300 °C, including 160 °C, 220 °C and 280 °C (Fig 4). Chen teaches the temperature is a result effective varying from 250-300 °C (Table VII, read on applicant's temperature value). The result effective variable is commonly determined by routine experiment. The process of conducting routine experiments so as to produce an expected result is obvious to one of ordinary skill in the art. Hence, it would have been obvious to one having ordinary skill in the art, at the time of invention, to perform routine experiment to obtain optimal temperature as an expected result.

Claims 12, 36-37, 40-41 differ from Liu and Narwankar by the specific flow rate of oxygen and nitrogen gas or the flow rate ratio of O₂: N₂. However, Chen clearly teaches the flow rate of oxygen and nitrogen and flow rate ratio of O₂:N₂ are a result effective variables (col. 7-88, col. 18). The result effective variables are commonly determined by routine experiment. The process of conducting routine experiments so as to produce an expected result is obvious to one of ordinary skill in the art. Hence, it would have been obvious to one having ordinary skill in the art, at the time of invention, to perform routine experiment to obtain optimal flow rate for oxygen and nitrogen as an expected result.

Respect to claims 35, 39, Liu and Narwankar fail to disclose the substrate is heated in a gas mixture of oxygen and nitrogen for a duration of about 10-20 seconds.

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However, Narwankar clearly teaches to heat a substrate in a gas mixture comprises oxygen and nitrogen (col. 7-8). Chen teaches the duration of heating is a result effective variable. Chen further teaches to heat a substrate in a mixture of nitrogen and oxygen for a duration of 15-30 seconds including 20 seconds (Table VII). The result effective variable is commonly determined by routine experiment. The process of conducting routine experiments so as to produce an expected result is obvious to one of ordinary skill in the art. Hence, it would have been obvious to one having ordinary skill in the art, at the time of invention, to perform routine experiment to obtain optimal duration as an expected result.

6. Claim 25 is rejected under 35 U.S.C. 103(a) as being unpatentable over Liu and Narwankar and as applied to claims 1-2, 4-8, 17-19, 21-22, 26-30, 38, 42 above, and further in view of Wu (US 6,133,102).

Respect to claim 25, Liu fails to disclose the etching the substrate with a gas mixture comprising a halogen gas and a reducing gas. However, Liu clearly teaches to etch polysilicon using halogen gas (i.e. CF₄, HBr, Cl₂; See Table 2). Wu teaches to polysilicon layer (120) by using halogen- containing gas (CF₄) in addition with hydrogen gas (read on reducing gas) or HBr/O₂ (col. 3 lines 41-51). It would have been obvious to one having ordinary skill in the art, at the time of invention, to modify Liu and Narwankar in view of Wu by using halogen gas and reducing gas (i.e. H₂) because equivalent and substitution of one for the other would produce an expected result

Allowable Subject Matter

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7. Claims 9, 13-16, 20, 31 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

- 8. Claims 43-50 are allowed.
- 9. The following is a statement of reasons for the indication of allowable subject matter: The reason for allowance was discussed in previous office action.

Conclusion

10. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

11. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Binh X. Tran whose telephone number is (571) 272-

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1469. The examiner can normally be reached on Monday-Thursday and every other Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nadine Norton can be reached on (571) 272-1465. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

BinhTran

Binh X. Tran